ABBOGIATION CONNECTING ELECTRONICS (MOUSTRIES*) international and Pan-American	kburn, Illinois. A	Il rights reserved un ntions.	nder both This doc level par	tument is	a declaration er	on of the substancompasses al	tances w 1 lower	vithin the manufacture level materials for wh	er listed	item. Note: if nanufacturer	the item is an as has engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute			<ul> <li>* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information</li> </ul>					on				
Supplier Information													
Company name* Company unique ID				Unique ID Authority					Response Date*				
nsemi									2024-04-10				
Contact Name	Title - Contact			Phone - Contact*				Email - Contact*					
Product-Env-Stewards	t-Env-Stewards Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Representative				Phone - Representative*				Email - Representative*					
Product-Env-Stewards Product Enviro Compliance			NA			Produ			oduct-Env-Stewards@onsemi.com				
Requester Item Number Mfr It	em Number	Mfr Item Name		Effe	ective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type	
PCA9	A9654EDR2G 8-bit I/O Expander		r for I2C Bus and SMB	ıs 2024	4-04-10	10 PH1		H1		142.69	mg	Each	
Manufacturing Proccess Information													
Terminal Plating / Grid Array Material	/ Grid Array Material Terminal Base Alloy J-S		-STD-020 MSL Rating		Peak Process Body Temperatur		perature	Max Time at Peak Tempera		ture Numb	er of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alloy 1					260	C		30	seco	nds 3			
Comments													
level 1 - maximum time at peak temperature during	soldering is 10-3	0 seconds											
For more information regarding material compositi	on please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth					
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the				
Supplier Digital Signature Ra	stislav Drska	Le							

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sign range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	2.73	mg	Supplier	Silicon (Si)	7440-21-3		2.73	mg	
Die Attach	4.85	mg	Supplier	Silver (Ag)	7440-22-4		3.6375	mg	
			Supplier	Epoxy resins	129915-35-1		1.2125	mg	
Lead Frame	75.92	mg	Supplier	Silver (Ag)	7440-22-4		0.7592	mg	
			Supplier	Zinc (Zn)	7440-66-6		0.1518	mg	
			Supplier	Iron (Fe)	7439-89-6		1.9739	mg	
			Supplier	Copper (Cu)	7440-50-8		73.035	mg	
Mold Compound-Black	55.11	mg		Epoxy Phenol Resin	proprietary data		5.7866	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		49.3234	mg	
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg	
Wire Bond - Au	0.35	mg	Supplier	Gold (Au)	7440-57-5		0.35	mg	

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signar range of distribution unless otherwise noted)